

## MM54HC373/MM74HC373 TRI-STATE® Octal D-Type Latch

### General Description

These high speed octal D-type latches utilize advanced silicon-gate CMOS technology. They possess the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads. Due to the large output drive capability and the TRI-STATE feature, these devices are ideally suited for interfacing with bus lines in a bus organized system.

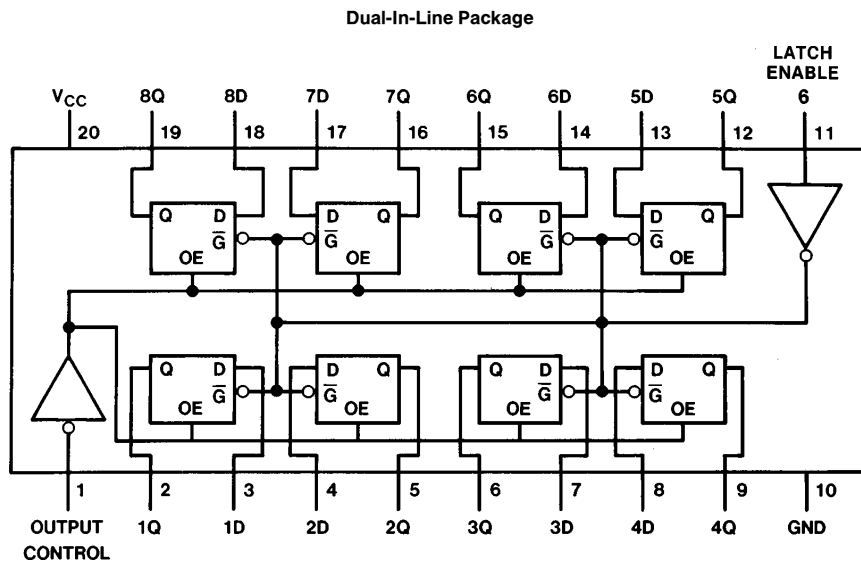
When the LATCH ENABLE input is high, the Q outputs will follow the D inputs. When the LATCH ENABLE goes low, data at the D inputs will be retained at the outputs until LATCH ENABLE returns high again. When a high logic level is applied to the OUTPUT CONTROL input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

The 54HC/74HC logic family is speed, function, and pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

### Features

- Typical propagation delay: 18 ns
- Wide operating voltage range: 2 to 6 volts
- Low input current: 1  $\mu$ A maximum
- Low quiescent current: 80  $\mu$ A maximum (74 Series)
- Output drive capability: 15 LS-TTL loads

### Connection Diagram



### Truth Table

Output Control	Latch Enable	Data	373 Output
L	H	H	H
L	H	L	L
L	L	X	$Q_0$
H	X	X	Z

H = high level, L = low level  
 $Q_0$  = level of output before steady-state input conditions were established.  
 Z = high impedance

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## Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage ( $V_{CC}$ )	-0.5 to +7.0V
DC Input Voltage ( $V_{IN}$ )	-1.5 to $V_{CC}$ + 1.5V
DC Output Voltage ( $V_{OUT}$ )	-0.5 to $V_{CC}$ + 0.5V
Clamp Diode Current ( $I_{IK}, I_{OK}$ )	±20 mA
DC Output Current, per pin ( $I_{OUT}$ )	±35 mA
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )	±70 mA
Storage Temperature Range ( $T_{STG}$ )	-65°C to +150°C
Power Dissipation ( $P_D$ ) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temp. ( $T_L$ ) (Soldering 10 seconds)	260°C

## Operating Conditions

	Min	Max	Units
Supply Voltage ( $V_{CC}$ )	2	6	V
DC Input or Output Voltage ( $V_{IN}, V_{OUT}$ )	0	$V_{CC}$	V
Operating Temp. Range ( $T_A$ )			
MM74HC	-40	+85	°C
MM54HC	-55	+125	°C
Input Rise or Fall Times ( $t_r, t_f$ )			
$V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

## DC Electrical Characteristics

Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ C$			Units	
				Typ	74HC $T_A = -40$ to $85^\circ C$	54HC $T_A = -55$ to $125^\circ C$		
$V_{IH}$	Minimum High Level Input Voltage		2.0V	1.5	1.5	1.5	V	
			4.5V	3.15	3.15	3.15	V	
			6.0V	4.2	4.2	4.2	V	
$V_{IL}$	Maximum Low Level Input Voltage**		2.0V	0.5	0.5	0.5	V	
			4.5V	1.35	1.35	1.35	V	
			6.0V	1.8	1.8	1.8	V	
$V_{OH}$	Minimum High Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V	2.0	1.9	1.9	V	
			4.5V	4.5	4.4	4.4	V	
			6.0V	6.0	5.9	5.9	V	
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 6.0$ mA $ I_{OUT}  \leq 7.8$ mA	4.5V	4.2	3.98	3.84	3.7	V
			6.0V	5.7	5.48	5.34	5.2	V
$V_{OL}$	Maximum Low Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 6.0$ mA $ I_{OUT}  \leq 7.8$ mA	4.5V	0.2	0.26	0.33	0.4	V
			6.0V	0.2	0.26	0.33	0.4	V
$I_{IN}$	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μA
$I_{OZ}$	Maximum TRI-STATE Output Leakage Current	$V_{IN} = V_{IH}$ or $V_{IL}$ , $OC = V_{IH}$ $V_{OUT} = V_{CC}$ or GND	6.0V		±0.5	±5	±10	μA
$I_{CC}$	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		8.0	80	160	μA

**Note 1:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.

**Note 2:** Unless otherwise specified all voltages are referenced to ground.

**Note 3:** Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

**Note 4:** For a power supply of 5V ±10% the worst case output voltages ( $V_{OH}$  and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5V$  and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

\*\* $V_{IL}$  limits are currently tested at 20% of  $V_{CC}$ . The above  $V_{IL}$  specification (30% of  $V_{CC}$ ) will be implemented no later than Q1, CY'89.

### AC Electrical Characteristics $V_{CC}=5V, T_A=25^{\circ}C, t_r=t_f=6\text{ ns}$

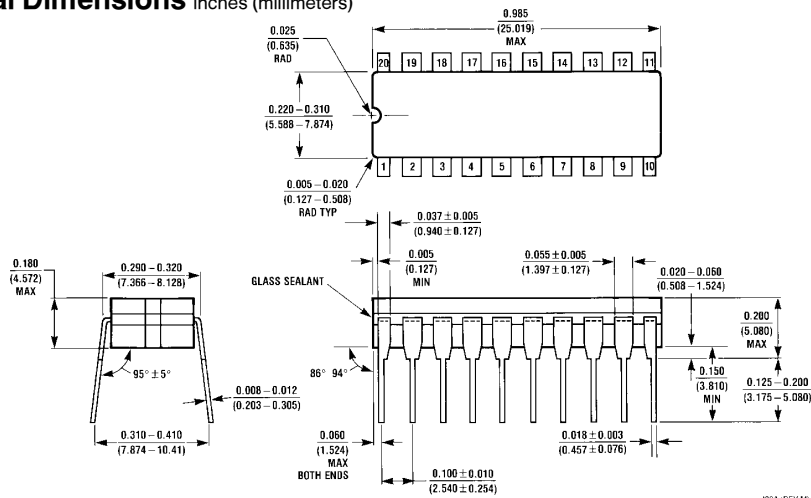
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, Data to Q	$C_L = 45\text{ pF}$	18	25	ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, LE to Q	$C_L = 45\text{ pF}$	21	30	ns
$t_{PZH}, t_{PZL}$	Maximum Output Enable Time	$R_L = 1\text{ k}\Omega$ $C_L = 45\text{ pF}$	20	28	ns
$t_{PHZ}, t_{PLZ}$	Maximum Output Disable Time	$R_L = 1\text{ k}\Omega$ $C_L = 5\text{ pF}$	18	25	ns
$t_S$	Minimum Set Up Time			5	ns
$t_H$	Minimum Hold Time			10	ns
$t_W$	Minimum Pulse Width		9	16	ns

### AC Electrical Characteristics $V_{CC}=2.0\text{--}6.0V, C_L=50\text{ pF}, t_r=t_f=6\text{ ns}$ (unless otherwise specified)

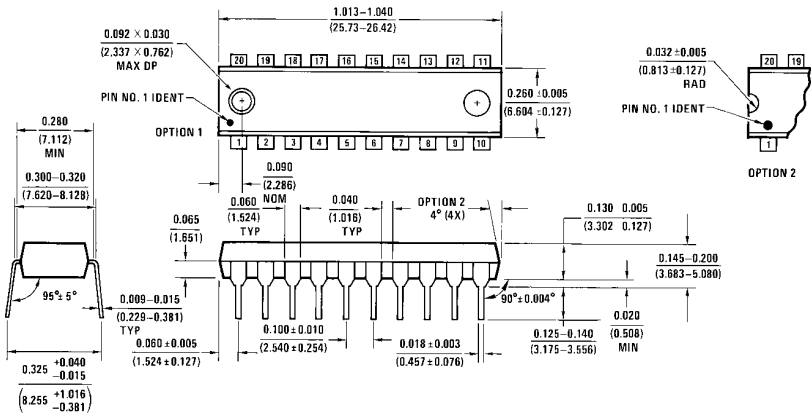
Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^{\circ}C$		74HC $T_A = -40\text{ to }85^{\circ}C$		54HC $T_A = -55\text{ to }125^{\circ}C$		Units
				Typ	Guaranteed Limits					
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, Data to Q	$C_L = 50\text{ pF}$	2.0V	50	150	188		225		ns
			2.0V	80	200	250		300		ns
		$C_L = 150\text{ pF}$	4.5V	22	30	37		45		ns
			4.5V	30	40	50		60		ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay, LE to Q	$C_L = 50\text{ pF}$	2.0V	63	175	220		263		ns
			2.0V	110	225	280		338		ns
		$C_L = 150\text{ pF}$	4.5V	25	35	44		52		ns
			4.5V	35	45	56		68		ns
$t_{PZH}, t_{PZL}$	Maximum Output Enable Time	$R_L = 1\text{ k}\Omega$	2.0V	50	150	188		225		ns
			2.0V	80	200	250		300		ns
		$C_L = 50\text{ pF}$	4.5V	21	30	37		45		ns
			4.5V	30	40	50		60		ns
$t_{PHZ}, t_{PLZ}$	Maximum Output Disable Time	$R_L = 1\text{ k}\Omega$	2.0V	50	150	188		225		ns
			4.5V	21	30	37		45		ns
		$C_L = 50\text{ pF}$	6.0V	19	26	31		39		ns
			6.0V	26	35	44		53		ns
$t_S$	Minimum Set Up Time		2.0V	50	60	75		ns		
			4.5V	9	13	15		ns		
			6.0V	9	11	13		ns		
$t_H$	Minimum Hold Time		2.0V	5	5	5		ns		
			4.5V	5	5	5		ns		
			6.0V	5	5	5		ns		
$t_W$	Minimum Pulse Width		2.0V	30	80	100		ns		
			4.5V	10	16	20		ns		
			6.0V	9	14	18		ns		
$t_{THL}, t_{TLH}$	Maximum Output Rise and Fall Time	$C_L = 50\text{ pF}$	2.0V	25	60	75		ns		
			4.5V	7	12	15		ns		
			6.0V	6	10	13		ns		
$C_{PD}$	Power Dissipation Capacitance (Note 5)	(per latch) $OC = V_{CC}$ $OC = GND$		30 50					pF pF	
$C_{IN}$	Maximum Input Capacitance			5	10	10		pF		
$C_{OUT}$	Maximum Output Capacitance			15	20	20		pF		

**Note 5:**  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} V_{CC} f + I_{CC}$ .

**Physical Dimensions** inches (millimeters)



**Ceramic Dual-In-Line Package (J)**  
**Order Number MM54HC373J or MM74HC373J**  
**NS Package Number J20A**



**Molded Dual-In-Line Package (N)**  
**Order Number MM74HC373N**  
**NS Package Number N20A**

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